



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  *: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2013-01-17
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS30L60CG-TR	7SD2*Z02Q02U	A	SH1A	2013-01-17
Amount	UoM	Unit type	ST ECOPACK Grade	
1440.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.20,9.15,4.5	2	gull wing	
Comment	D2 D2PAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList :REACH-18 June 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	75D2*Z02Q02U					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	14.44	mg	supplier	die	Silicon (Si)	7440-21-3		13.719	mg	950069	9527
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.569	mg	39404	395
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.013	mg	900	9
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.02	mg	1385	14
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.015	mg	1039	10
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.084	mg	5817	58
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.02	mg	1385	14
Leadframe	Copper & its alloys	779.811	mg	supplier	alloy	Copper (Cu)	7440-50-8		775.98	mg	895087	538875
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.357	mg	458	248
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.653	mg	837	453
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		2.804	mg	3596	1947
Leadframe				supplier	metallization	Phosphorus (P)	12185-10-3		0.017	mg	22	12
Soft solder	Solder	9.532	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	9.103	mg	954994	6322
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.238	mg	24969	165
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.191	mg	20038	133
Bonding wire	Other inorganic materials	4.05	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.05	mg	1000000	2813
encapsulation	Other Organic Materials	629.678	mg	supplier	mold compound	Silica, vitreous	60676-86-0		503.743	mg	800001	349822
encapsulation				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		44.077	mg	69999	30609
encapsulation				supplier	mold compound	Phenol resin	9003-35-4		25.187	mg	40000	17491
encapsulation				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		37.781	mg	60001	26237
encapsulation				supplier	mold compound	Antimony Trioxide	1309-64-4		7.556	mg	12000	5247
encapsulation				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		9.445	mg	15000	6559
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.889	mg	3000	1312
connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1728